

TK15J50D-VB Datasheet

N-Channel 600 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	600					
R _{DS(on)} at 25 °C (Ω)	$V_{GS} = 10 V$	0.23				
Q _g Typ. (nC)	24					
Q _{gs} (nC)	6					
Q _{gd} (nC)	11					
Configuration	Single					

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)



TO-3P G G D D (TAB) S s

- **APPLICATIONS**
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)									
PARAMETER			SYMBOL	LIMIT	UNIT				
Drain-Source Voltage			V _{DS}	600	V				
Gate-Source Voltage			V _{GS}	± 30					
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	15					
		T _C = 100 °C		10	А				
Pulsed Drain Current ^a			I _{DM}	45					
Linear Derating Factor				1.4	W/°C				
Single Pulse Avalanche Energy ^b			E _{AS}	286	mJ				
Maximum Power Dissipation			PD	180	W				
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C				
Drain-Source Voltage Slope	T _J = 125 °C		d\//dt	37					
Reverse Diode dV/dt ^d			dV/dt	23	V/ns				
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C				

N-Channel MOSFET

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD} = 50$ V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.5 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.



THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	- 62				°C 44		
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.7				°C/W		
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$, u		1			1	1	1	1
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D =	250 µA	600	-	-	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 1 mA	-	0.75	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V
	1	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 30 \text{ V}$			-	-	± 1	μA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			-	-	1	μA
		V _{DS} = 520 V	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			-	10	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		I _D = 8 A	-	0.23	-	Ω
Forward Transconductance	g fs	V _{DS}	= 30 V, I _D	= 8 A	-	5.6	-	S
Dynamic		1			1	1	1	1
Input Capacitance	C _{iss}		V _{GS} = 0 \	1	-	1640	-	
Output Capacitance	C _{oss}	-	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$		-	80	-	1
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	4	-	pF	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V_{DS} = 0 V to 520 V, V_{GS} = 0 V		-	63	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	213	-		
Total Gate Charge	Qg				-	24	48	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V I _D = 8 A		A, V _{DS} = 520 V	-	6	-	
Gate-Drain Charge	Q _{gd}				-	11	-	
Turn-On Delay Time	t _{d(on)}				-	18	36	
Rise Time	t _r	V _{DD} = 520V, I _D = 8 A,		-	24	48	ns	
Turn-Off Delay Time	t _{d(off)}		$V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$		-	48	96	115
Fall Time	t _f			-	25	50		
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.8	-	Ω	
Drain-Source Body Diode Characteristic	cs	1						1
Continuous Source-Drain Diode Current	I _S	MOSFET syml showing the	MOSFET symbol showing the		-	-	15	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	38	A	
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 8 \text{ A},$ dl/dt = 100 A/µs, V _R = 400 V		-	325	-	ns	
Reverse Recovery Charge	Q _{rr}			_	4.6	_	μC	
Reverse Recovery Current				-	20	_	A	
neverse necovery ourient	I _{RRM}			-	20	-	Ā	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

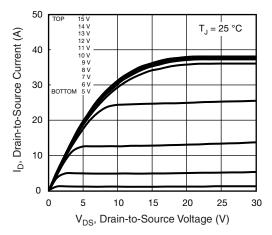


Fig. 1 - Typical Output Characteristics

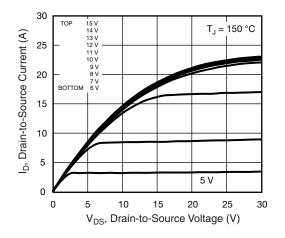


Fig. 2 - Typical Output Characteristics

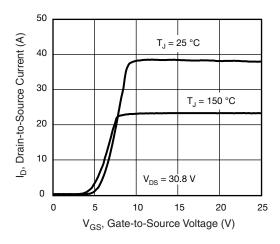


Fig. 3 - Typical Transfer Characteristics

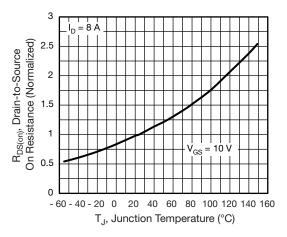


Fig. 4 - Normalized On-Resistance vs. Temperature

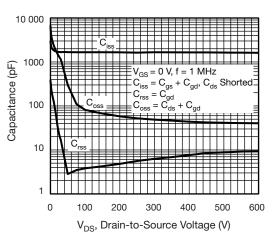


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

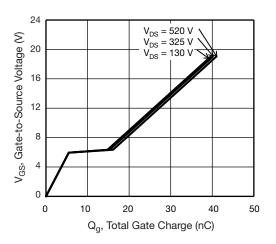


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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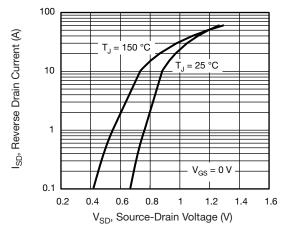


Fig. 7 - Typical Source-Drain Diode Forward Voltage

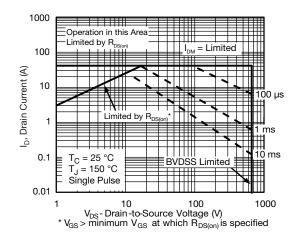


Fig. 8 - Maximum Safe Operating Area

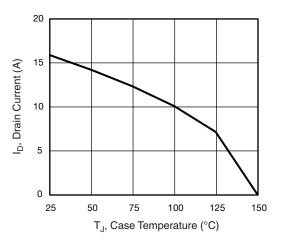


Fig. 9 - Maximum Drain Current vs. Case Temperature

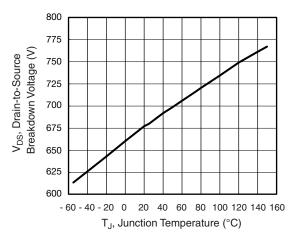


Fig. 10 - Temperature vs. Drain-to-Source Voltage

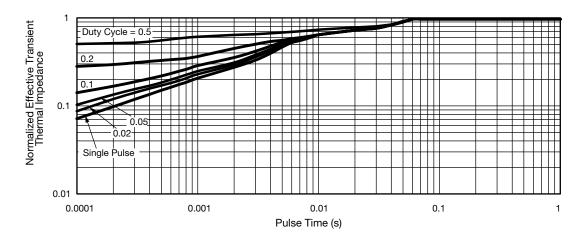


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



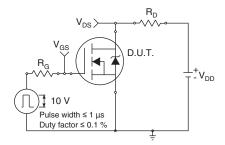


Fig. 12 - Switching Time Test Circuit

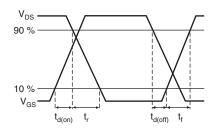


Fig. 13 - Switching Time Waveforms

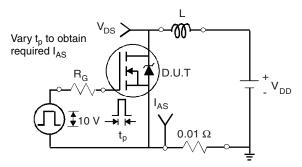


Fig. 14 - Unclamped Inductive Test Circuit

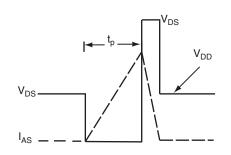


Fig. 15 - Unclamped Inductive Waveforms

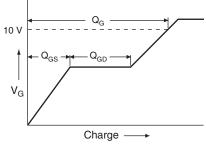


Fig. 16 - Basic Gate Charge Waveform

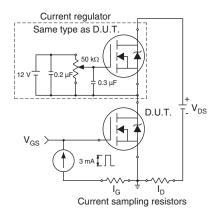
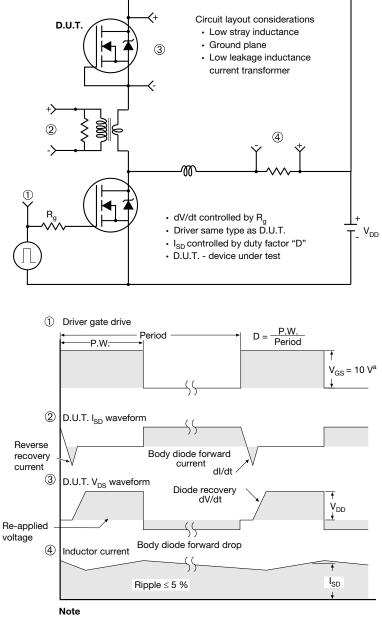


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit

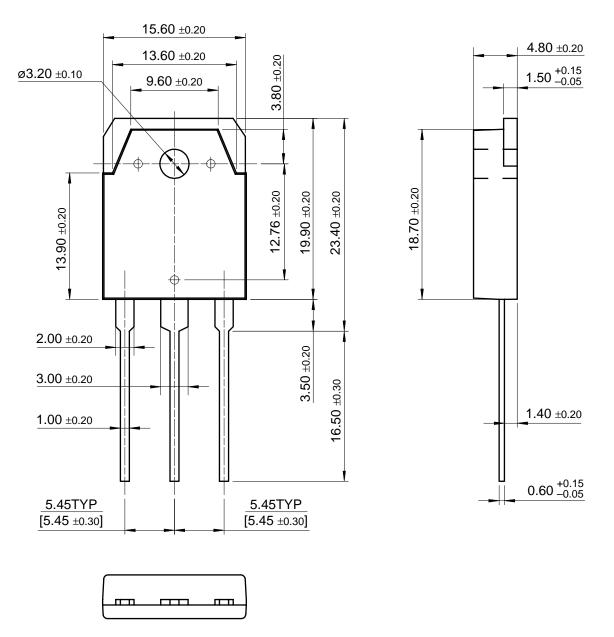


a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel



TO-3P





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